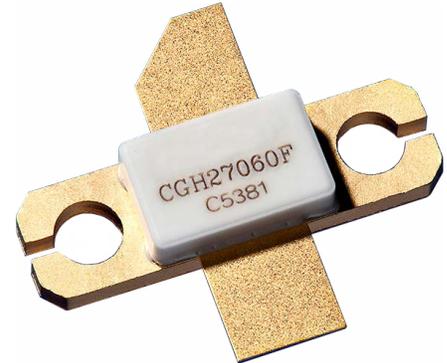


CGH27060F

60 W Peak, 28 V, GaN HEMT for Linear Communications from VHF to 3 GHz



Description

The CGH27060F is a gallium nitride (GaN) high electron mobility transistor (HEMT) designed specifically for high efficiency, high gain and wide bandwidth capabilities, which makes the CGH27060F ideal for VHF, Comms, 3G, 4G, LTE, 2.3-2.9GHz WiMAX and BWA amplifier applications. The unmatched transistor is supplied in a ceramic/metal flange package.

Package Types: 440193
PN: CGH27060F

Typical Performance Over 2.3-2.7 GHz ($T_c = 25^\circ\text{C}$) of Demonstration Amplifier

Parameter	2.3 GHz	2.4 GHz	2.5 GHz	2.6 GHz	2.7 GHz	Units
Small Signal Gain	15.1	14.7	14.3	14.3	14.5	dB
EVM @ 39 dBm	2.35	2.16	2.01	2.13	2.82	%
Drain Efficiency @ 39 dBm	28.3	27.6	27.3	26.7	26.3	%
Input Return Loss	10.0	7.3	6.0	7.0	10.3	dB

Note:

Measured in the CGH27060F-AMP amplifier circuit, under 802.16 OFDM, 3.5 MHz Channel BW, 1/4 Cyclic Prefix, 64 QAM Modulated Burst, 5ms Burst, Symbol Length of 59, Coding Type RS-CC, Coding Rate Type 2/3, PAR = 9.8 dB @ 0.01% Probability on CCDF

Features

- VHF - 3.0 GHz Operation
- 14 dB Small Signal Gain
- 8.0 W P_{AVE} at < 2.0% EVM
- 27% Drain Efficiency at 8 W Average Power
- WiMAX Fixed Access 802.16-2004 OFDM
- WiMAX Mobile Access 802.16e OFDMA

Large Signal Models Available for ADS and MWO



Absolute Maximum Ratings (not simultaneous) at 25°C Case Temperature

Parameter	Symbol	Rating	Units	Conditions
Drain-Source Voltage	V_{DSS}	120	V	25°C
Gate-to-Source Voltage	V_{GS}	-10, +2		
Storage Temperature	T_{STG}	-65, +150	°C	
Operating Junction Temperature	T_J	225		
Maximum Forward Gate Current	I_{GMAX}	15	mA	25°C
Maximum Drain Current ¹	I_{DMAX}	6	A	
Soldering Temperature ²	T_S	245	°C	
Screw Torque	τ	40	in-oz	
Thermal Resistance, Junction to Case ³	$R_{\theta JC}$	2.8	°C/W	85°C
Case Operating Temperature ³	T_C	-40, +150	°C	

Notes:

¹ Current limit for long term, reliable operation

² Refer to the Application Note on soldering

³ Measured for the CGH27060F at $P_{DSS} = 56$ W.

Electrical Characteristics ($T_c = 25^\circ\text{C}$)

Characteristics	Symbol	Min.	Typ.	Max.	Units	Conditions
DC Characteristics¹						
Gate Threshold Voltage	$V_{GS(th)}$	-3.5	-3.0	-2.0	V_{DC}	$V_{DS} = 10$ V, $I_D = 14.4$ mA
Gate Quiescent Voltage	$V_{GS(Q)}$	–	-2.7	–		$V_{DS} = 28$ V, $I_{DQ} = 300$ mA
Saturated Drain Current	I_{DS}	11.6	14.0	–	A	$V_{DS} = 6.0$ V, $V_{GS} = 2$ V
Drain-Source Breakdown Voltage	V_{BR}	84	–	–	V_{DC}	$V_{GS} = -8$ V, $I_D = 14.4$ mA
RF Characteristics^{2,3} ($T_c = 25^\circ\text{C}$, $F_0 = 2.5$ GHz unless otherwise noted)						
Small Signal Gain	G_{SS}	11.0	13.0	–	dB	$V_{DD} = 28$ V, $I_{DQ} = 300$ mA
Drain Efficiency ⁴	η	21	24	–	%	$V_{DD} = 28$ V, $I_{DQ} = 300$ mA, $P_{AVE} = 8$ W
Error Vector Magnitude	EVM	–	2.0	–		
Output Mismatch Stress	VSWR	–	–	10:1	Ψ	No damage at all phase angles, $V_{DD} = 28$ V, $I_{DQ} = 300$ mA, $P_{AVE} = 8$ W
Dynamic Characteristics						
Input Capacitance	C_{GS}	–	19.0	–	pF	$V_{DS} = 28$ V, $V_{GS} = -8$ V, $f = 1$ MHz
Output Capacitance	C_{DS}	–	5.9	–		
Feedback Capacitance	C_{GD}	–	0.8	–		

Notes:

¹ Measured on wafer prior to packaging.

² Measured in the CGH27060F-AMP test fixture

³ Under 802.16 OFDM, 3.5 MHz Channel BW, 1/4 Cyclic Prefix, 64 QAM Modulated Burst, 5ms Burst, Symbol Length of 59, Coding Type RS-CC, Coding Rate Type 2/3, PAR = 9.8 dB @ 0.01% Probability on CCDF

⁴ Drain Efficiency = P_{OUT} / P_{DC}

Typical WiMAX Performance

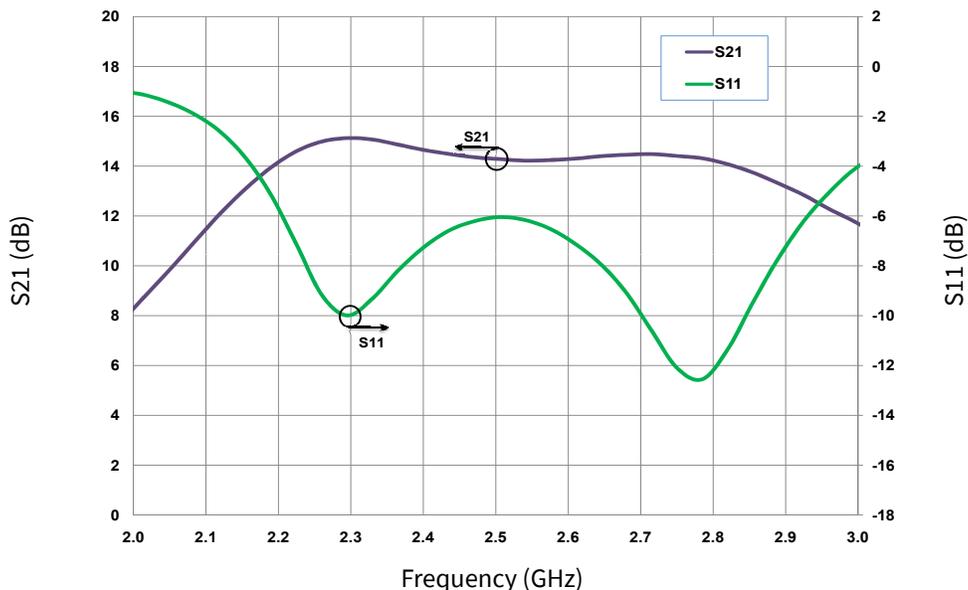


Figure 1. Gain and Return Loss vs Frequency measured in Broadband Amplifier Circuit CGH27060F-AMP
 $V_{DD} = 28\text{ V}$, $I_{DQ} = 300\text{ mA}$

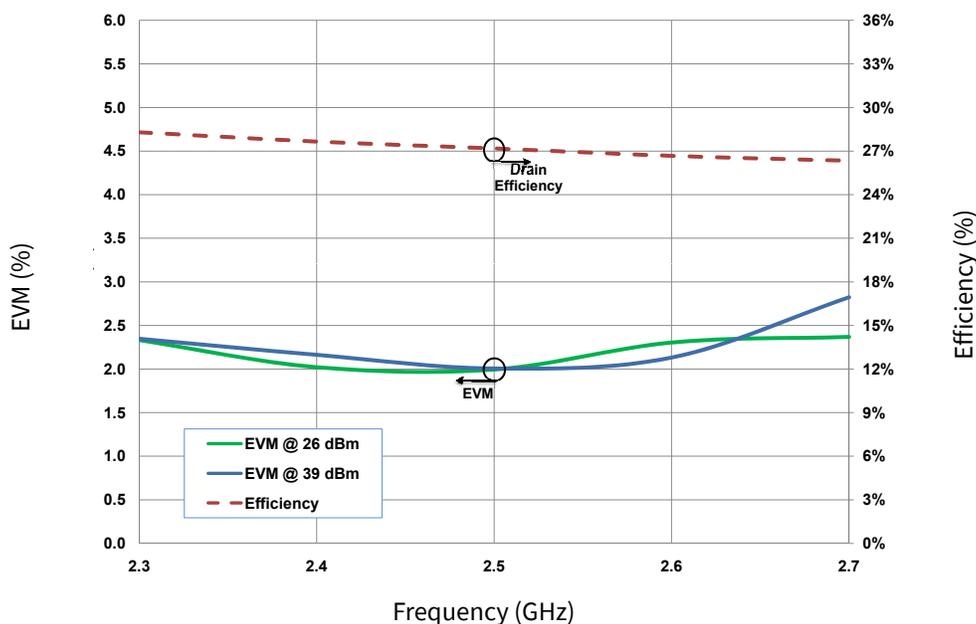


Figure 2. Typical EVM at 24 dBm and 39 dBm vs Frequency measured in Broadband Amplifier Circuit CGH27060F-AMP

Note:
¹ Under 802.16-2004 OFDM, 3.5 MHz Channel BW, 1/4 Cyclic Prefix, 64 QAM Modulated Burst, Symbol Length of 59, Coding Type RS-CC, Coding Rate Type 2/3.

Typical WiMAX Performance

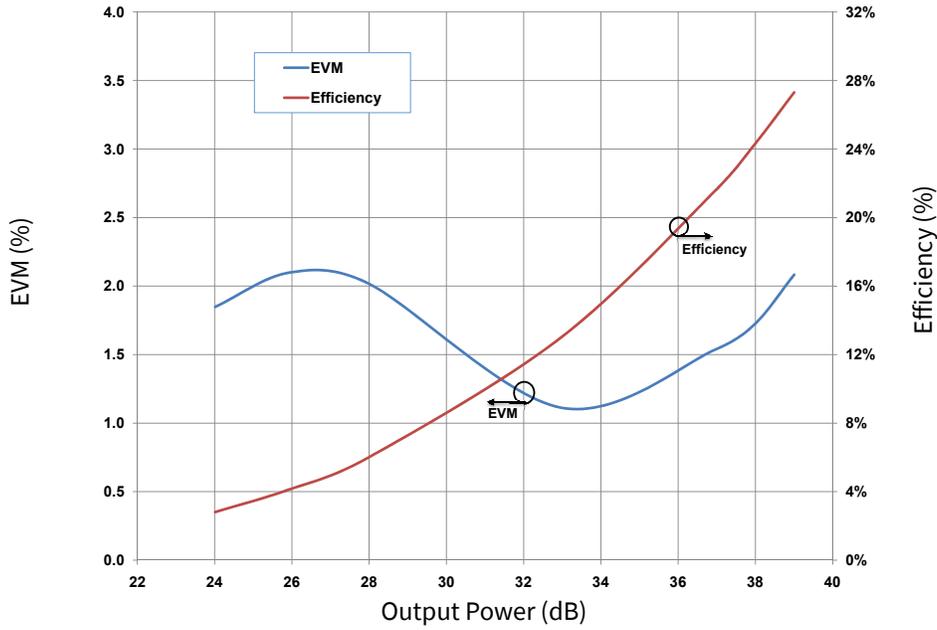


Figure 3. Drain Efficiency and EVM vs Output Power measured in CGH27060F-AMP
 $V_{DD} = 28\text{ V}$, $I_{DQ} = 300\text{ mA}$, 802.16-2004 OFDM, PAR = 9.8 dB

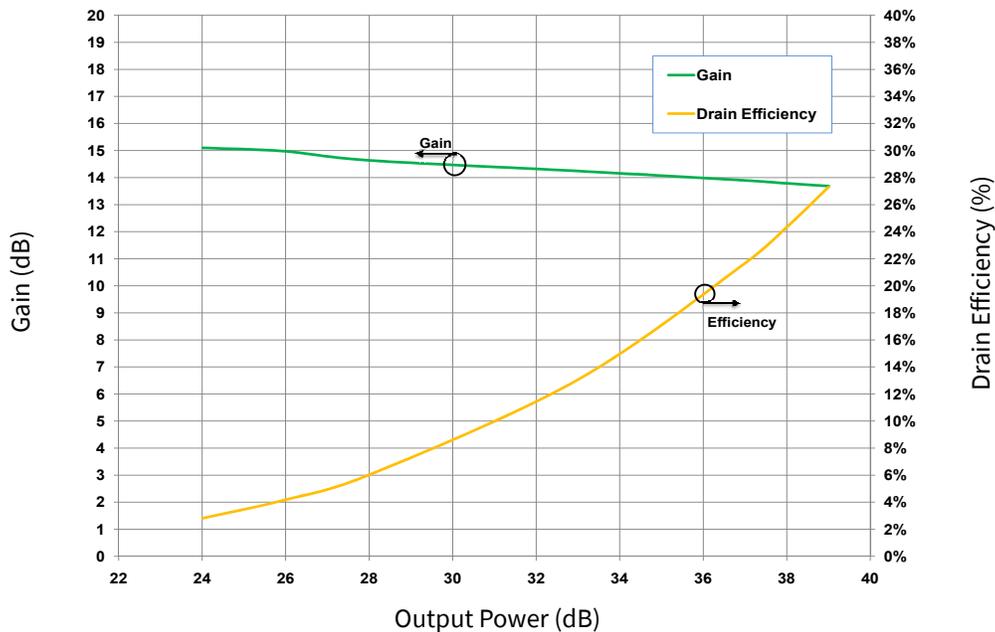


Figure 4. Typical Gain and Efficiency vs Output Power measured in CGH27060F-AMP
 $V_{DD} = 28\text{ V}$, $I_{DQ} = 300\text{ mA}$, 802.16-2004 OFDM, PAR = 9.8 dB

Note:
¹ Under 802.16-2004 OFDM, 3.5 MHz Channel BW, 1/4 Cyclic Prefix, 64 QAM Modulated Burst, Symbol Length of 59, Coding Type RS-CC, Coding Rate Type 2/3.

Typical Performance

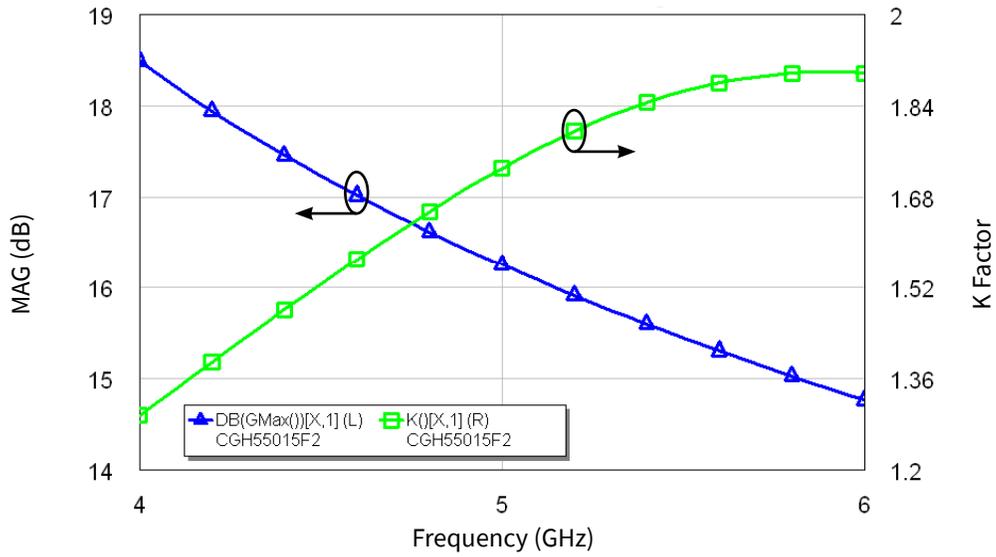


Figure 5. Simulated Maximum Available Gain and K Factor of the CGH27060F
 $V_{DD} = 28\text{ V}$, $I_{DQ} = 300\text{ mA}$

Typical Noise Performance

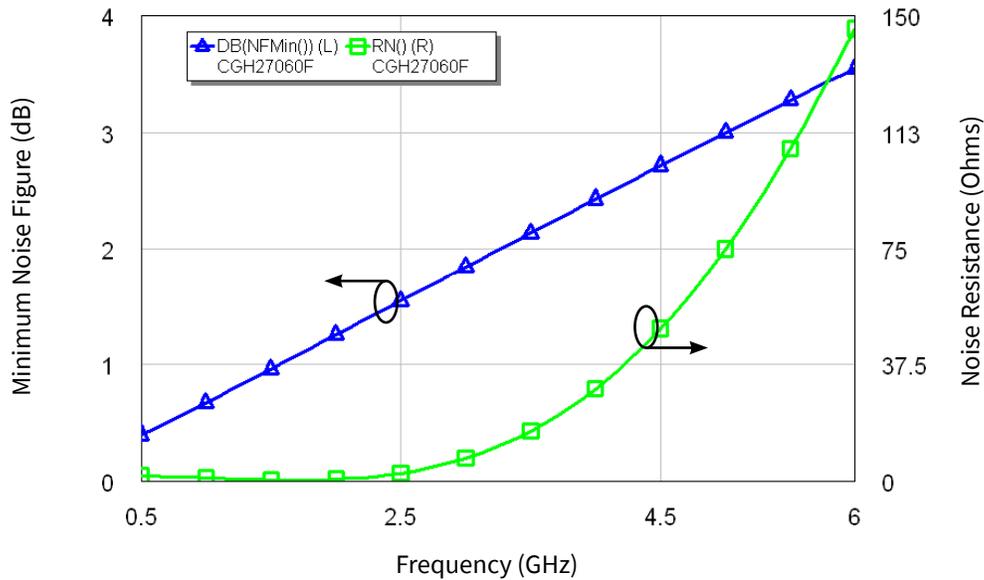
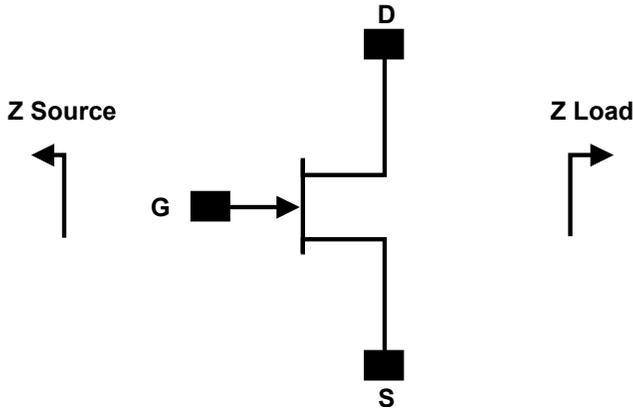


Figure 6. Simulated Minimum Noise Figure and Noise Resistance vs Frequency of the CGH27060
 $V_{DD} = 28\text{ V}$, $I_{DQ} = 100\text{ mA}$

Electrostatic Discharge (ESD) Classifications

Parameter	Symbol	Class	Classification Level	Test Methodology
Human Body Model	HBM	TBD	ANSI/ESDA/JEDEC JS-001 Table 3	JEDEC JESD22 A114-D
Charge Device Model	CDM	TBD	ANSI/ESDA/JEDEC JS-002 Table 3	JEDEC JESD22 C101-C

Source and Load Impedances



Frequency	Z Source	Z Lead
500	3.34 + j4.56	10.8 - j8.24
1000	2.07 - j0.05	6.18 - j4.17
2000	1.3 - j3.37	4.65 - j0.05
3000	1.64 - j8.15	4.75 - j3.4
4000	1.9 - j10.8	4.56 - j7.9

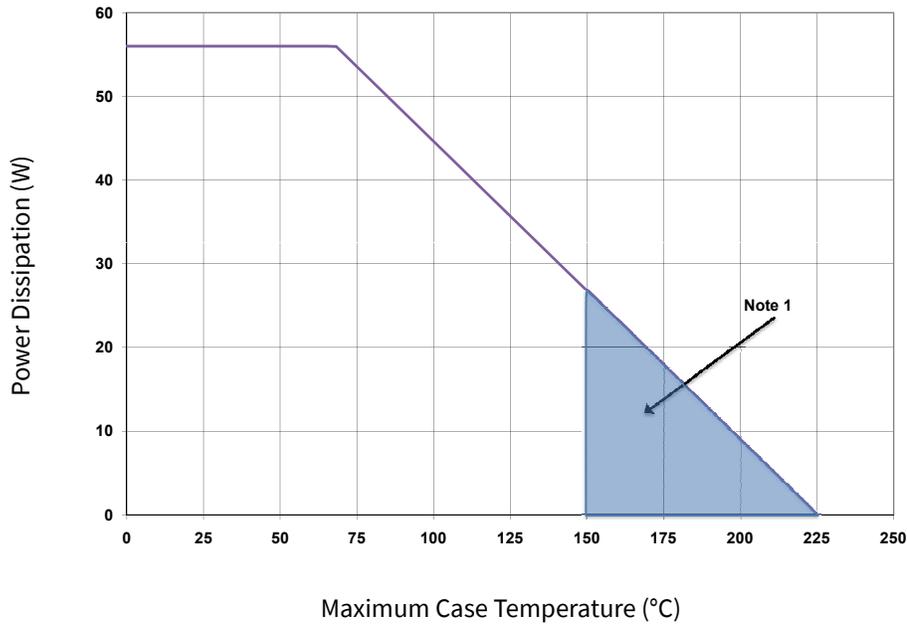
Notes:

¹ $V_{DD} = 28V, I_{DQ} = 300mA$ in the 440193 package

² Optimized for P_{SAT} and PAE

³ When using this device at low frequency, series resistors should be used to maintain amplifier stability

CGH27060F Power Dissipation De-rating Curve

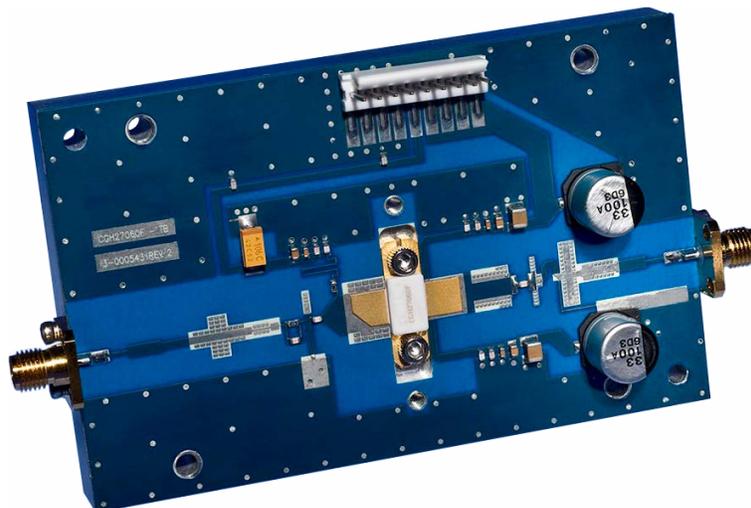


Note: Area exceeds Maximum Case Operating Temperature (See Page 2)

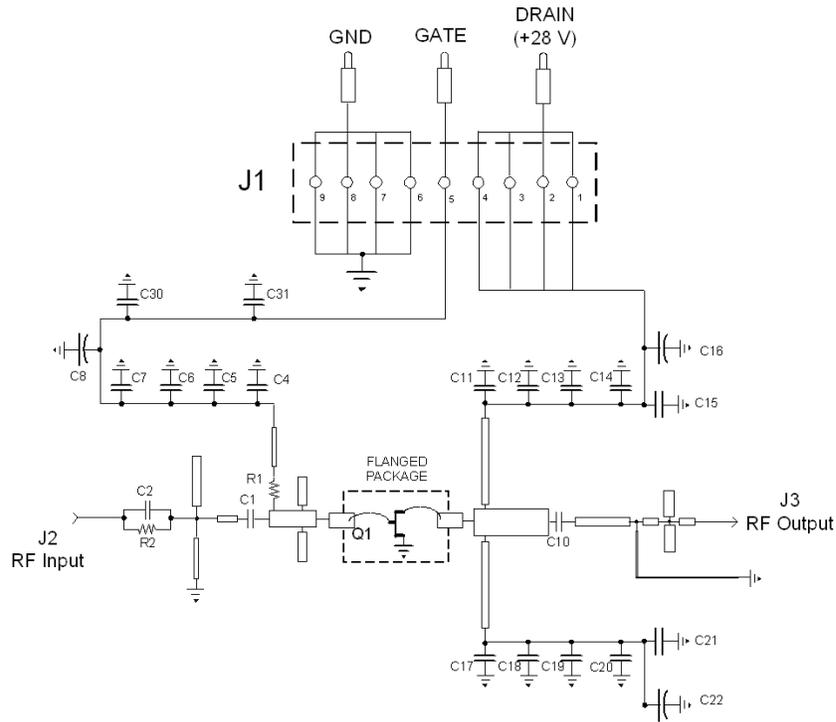
CGH27060F-AMP Demonstration Amplifier Circuit Bill of Materials

Designator	Description	Qty
R1	RES, 1/16W, 0603, 1%, 5.1 OHMS	1
R2	RES, 1/16W, 0603, 1%, 100 OHMS	1
C6, C13, C19	CAP, 470pF, 10%, 100V, 0603	3
C16, C22	CAP, 33μF, 20%, G CASE	1
C15, C21	CAP, 1.0μF, 100V, 10%, X7R, 1210	1
C8	CAP 10μF 16V TANTALUM	1
C10	CAP, 8.2pF, +/-5%, 100B	1
C1	CAP, 0.9pF, +/-0.05pF, 0603	1
C2	CAP, 2.2pF, +/-0.1pF, 0603	1
C10, C11, C17	CAP, 10.0pF, +/-5%, 0603	3
C5, C12, C18, C30, C31	CAP, 82pF, +/-5%, 0603	5
C7, C14, C20	CAP, 33000pF, 0805, 100V, X7R	3
J2, J3	CONN SMA STR PANEL JACK RECP	1
J1	HEADER RT>PLZ .1CEN LK 9POS	1
-	PCB, RO4350B, Er = 3.48, h = 20 mil	1
-	CGH27060F	1

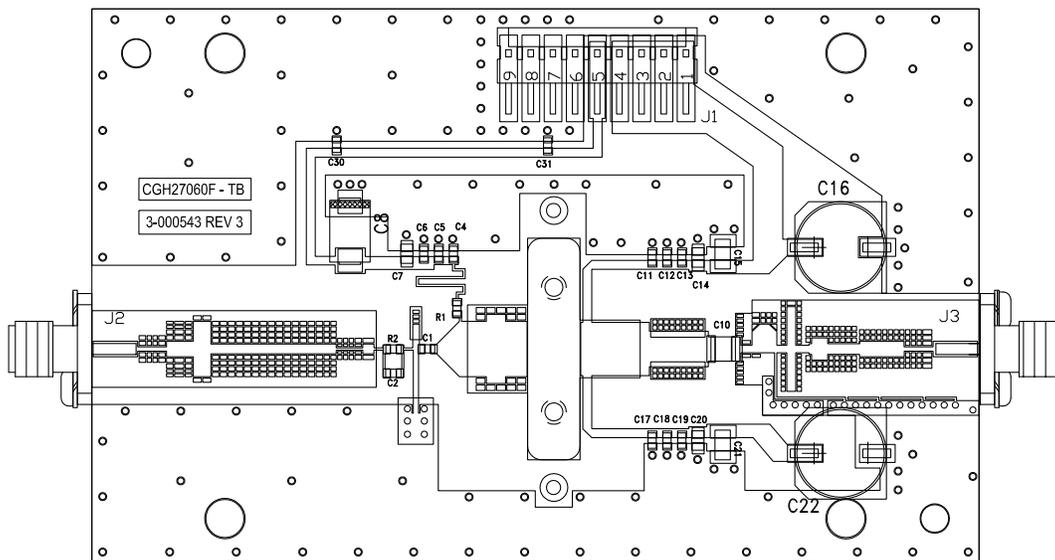
CGH27060F-AMP Demonstration Amplifier Circuit



CGH27060F-AMP Demonstration Amplifier Circuit Schematic



CGH27060F-AMP Demonstration Amplifier Circuit Outline

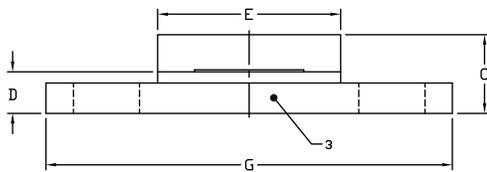
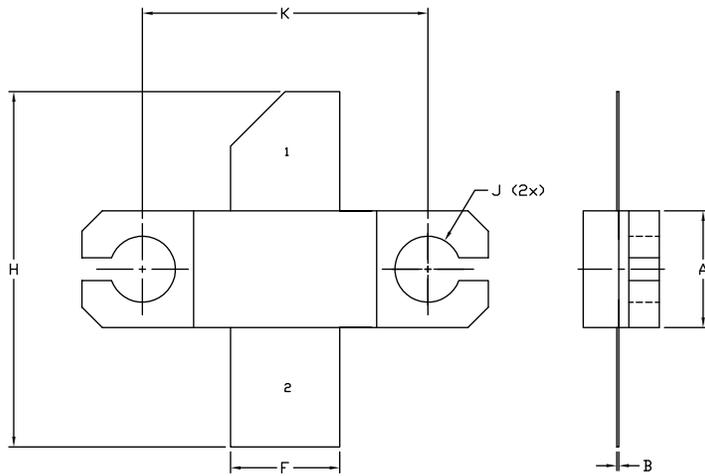


Typical Package S-Parameters for CGH27060F
(Small Signal, $V_{DS} = 28\text{ V}$, $I_{DQ} = 300\text{ mA}$, angle in degrees)

Frequency	Mag S11	Ang S11	Mag S21	Ang S21	Mag S12	Ang S12	Mag S22	Ang S22
500 MHz	0.935	-171.10	7.31	80.30	0.013	-4.81	0.629	-171.50
600 MHz	0.935	-173.48	6.08	76.43	0.013	-7.68	0.635	-171.81
700 MHz	0.936	-175.34	5.20	72.85	0.013	-10.25	0.642	-171.96
800 MHz	0.937	-176.87	4.54	69.47	0.013	-12.62	0.649	-172.04
900 MHz	0.937	-178.19	4.03	66.24	0.013	-14.82	0.656	-172.11
1.0 GHz	0.938	-179.38	3.62	63.13	0.013	-16.89	0.664	-172.18
1.1 GHz	0.939	-179.54	3.28	60.12	0.013	-18.84	0.672	-172.28
1.2 GHz	0.939	-178.52	3.00	57.20	0.012	-20.69	0.680	-172.42
1.3 GHz	0.940	-177.55	2.77	54.36	0.012	-22.44	0.688	-172.60
1.4 GHz	0.941	-176.60	2.57	51.59	0.012	-24.10	0.695	-172.83
1.5 GHz	0.942	-175.68	2.39	48.89	0.012	-25.67	0.703	-173.11
1.6 GHz	0.942	-174.77	2.24	46.24	0.012	-27.15	0.710	-173.42
1.7 GHz	0.943	-173.87	2.11	43.66	0.012	-28.56	0.718	-173.78
1.8 GHz	0.943	-172.96	2.00	41.12	0.011	-29.88	0.724	-174.18
1.9 GHz	0.944	-172.04	1.90	38.63	0.011	-31.12	0.731	-174.61
2.0 GHz	0.944	-171.11	1.81	36.19	0.011	-32.29	0.737	-175.07
2.1 GHz	0.944	-170.16	1.73	33.78	0.011	-33.39	0.743	-175.57
2.2 GHz	0.944	-169.19	1.67	31.41	0.011	-34.42	0.748	-176.10
2.3 GHz	0.945	-168.19	1.61	29.06	0.011	-35.38	0.753	-176.65
2.4 GHz	0.944	-167.16	1.55	26.74	0.010	-36.28	0.758	-177.23
2.5 GHz	0.944	-166.10	1.51	24.43	0.010	-37.11	0.762	-177.83
2.6 GHz	0.944	-165.00	1.47	22.14	0.010	-37.88	0.765	-178.45
2.7 GHz	0.944	-163.85	1.43	19.85	0.010	-38.60	0.769	-179.10
2.8 GHz	0.943	-162.64	1.41	17.56	0.010	-39.27	0.771	-179.77
2.9 GHz	0.942	-161.38	1.38	15.27	0.010	-39.90	0.774	-179.54
3.0 GHz	0.941	-160.06	1.36	12.96	0.010	-40.48	0.776	-178.82
3.2 GHz	0.939	-157.18	1.34	8.27	0.010	-41.54	0.778	-177.32
3.4 GHz	0.935	-153.93	1.33	3.43	0.010	-42.52	0.779	-175.73
3.6 GHz	0.931	-150.21	1.34	-1.65	0.010	-43.50	0.778	-174.01
3.8 GHz	0.925	-145.88	1.37	-7.06	0.010	-44.60	0.774	-172.17
4.0 GHz	0.916	-140.74	1.43	-12.95	0.011	-45.95	0.769	-170.17
4.2 GHz	0.906	-134.55	1.50	-19.47	0.011	-47.77	0.760	-167.98
4.4 GHz	0.891	-126.90	1.61	-26.85	0.012	-50.32	0.749	-165.56
4.6 GHz	0.872	-117.26	1.75	-35.39	0.013	-53.96	0.733	-162.84
4.8 GHz	0.848	-104.85	1.92	-45.48	0.014	-59.15	0.713	-159.74
5.0 GHz	0.817	-88.57	2.14	-57.60	0.016	-66.44	0.688	-156.11
5.2 GHz	0.784	-67.16	2.37	-72.25	0.018	-76.37	0.654	-151.74
5.4 GHz	0.759	-39.85	2.58	-89.71	0.020	-89.30	0.609	-146.35
5.6 GHz	0.757	-8.00	2.70	-109.65	0.021	-104.92	0.546	-139.55
5.8 GHz	0.788	-24.14	2.67	-130.98	0.022	-122.14	0.460	-130.98
6.0 GHz	0.836	-52.18	2.49	-152.33	0.021	-139.60	0.347	-119.94

To download the s-parameters in s2p format, go to the CGH27060F Product Page.

Product Dimensions CGH27060F (Package Type — 440193)



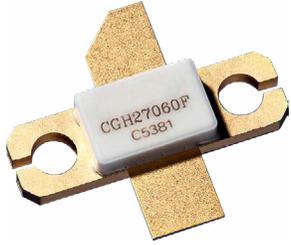
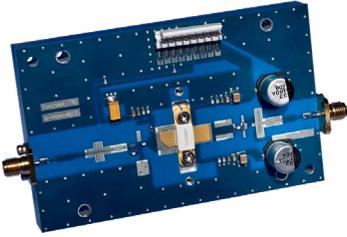
NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. ADHESIVE FROM LID MAY EXTEND A MAXIMUM OF 0.020" BEYOND EDGE OF LID.
4. LID MAY BE MISALIGNED TO THE BODY OF THE PACKAGE BY A MAXIMUM OF 0.008" IN ANY DIRECTION.
5. ALL PLATED SURFACES ARE Ni/AU

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.225	0.235	5.72	5.97
B	0.004	0.006	0.10	0.15
C	0.145	0.165	3.68	4.19
D	0.077	0.087	1.96	2.21
E	0.355	0.365	9.02	9.27
F	0.210	0.220	5.33	5.59
G	0.795	0.805	20.19	20.45
H	0.670	0.730	17.02	18.54
J	Ø .130		3.30	
k	0.562		14.28	

- PIN 1. GATE
 PIN 2. DRAIN
 PIN 3. SOURCE

Product Ordering Information

Order Number	Description	Unit of Measure	Image
CGH27060F	GaN HEMT	Each	
CGH27060F-AMP	Test board with GaN HEMT installed	Each	

Notes & Disclaimer

MACOM Technology Solutions Inc. ("MACOM"). All rights reserved.

These materials are provided in connection with MACOM's products as a service to its customers and may be used for informational purposes only. Except as provided in its Terms and Conditions of Sale or any separate agreement, MACOM assumes no liability or responsibility whatsoever, including for (i) errors or omissions in these materials; (ii) failure to update these materials; or (iii) conflicts or incompatibilities arising from future changes to specifications and product descriptions, which MACOM may make at any time, without notice. These materials grant no license, express or implied, to any intellectual property rights.

THESE MATERIALS ARE PROVIDED "AS IS" WITH NO WARRANTY OR LIABILITY, EXPRESS OR IMPLIED, RELATING TO SALE AND/OR USE OF MACOM PRODUCTS INCLUDING FITNESS FOR A PARTICULAR PURPOSE, MERCHANTABILITY, INFRINGEMENT OF INTELLECTUAL PROPERTY RIGHT, ACCURACY OR COMPLETENESS, OR SPECIAL, INDIRECT, INCIDENTAL, OR CONSEQUENTIAL DAMAGES WHICH MAY RESULT FROM USE OF THESE MATERIALS.

MACOM products are not intended for use in medical, lifesaving or life sustaining applications. MACOM customers using or selling MACOM products for use in such applications do so at their own risk and agree to fully indemnify MACOM for any damages resulting from such improper use or sale.